

# Semiconductor Packaging Market: Trends, Opportunities and Competitive Analysis [2023-2028]

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## Abstracts

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### Semiconductor Packaging Market Trends and Forecast

The future of the semiconductor packaging market looks promising with opportunities in the consumer electronics, automotive, healthcare, IT & telecommunication, and aerospace & defense end use industries. The global semiconductor packaging market is expected to reach an estimated \$29.2 billion by 2028 with a CAGR of 9.0% from 2023 to 2028. The major drivers for this market are an increase in demand for advanced packaging in consumer electronics and industrial products along with growing trend of miniaturization globally.

A more than 150-page report is developed to help in your business decisions. Sample figures with some insights are shown below.

### Semiconductor Packaging Market by Segment

The study includes a forecast for the global semiconductor packaging market by semiconductor packaging market by type, technology, end use industry, and region, as follows:

Semiconductor Packaging Market by Type [Value (\$B) Shipment Analysis from 2017 to 2028]:

Flip Chip

Embedded Die

Fan-in WLP

Fan-ut WLP

Semiconductor Packaging Market by Technology [Value (\$B) Shipment Analysis from 2017 to 2028]:

Grid Array

Small Outline Package

Flat no-leads Package

Dual in-line Packaging

Semiconductor Packaging Market by Technology [Value (\$B) Shipment Analysis from 2017 to 2028]:

Consumer Electronics

Automotive

Healthcare

IT & Telecommunication

Aerospace & Defense

Others

Semiconductor Packaging Market by Region [Value (\$B) Shipment Analysis from 2017 to 2028]:

North America

Europe

Asia Pacific

The Rest of the World

## List of Semiconductor Packaging Companies

Companies in the market compete on the basis of product quality offered. Major players in this market focus on expanding their manufacturing facilities, R&D investments, infrastructural development, and leverage integration opportunities across the value chain. With these strategies semiconductor packaging companies cater increasing demand, ensure competitive effectiveness, develop innovative products & technologies, reduce production costs, and expand their customer base. Some of the semiconductor packaging companies profiled in this report includes.

Amkor Technology

ASE Technology Holding Co.

Siliconware Precision Industries Co.

S?SS MICROTEC SE

Jiangsu Changjiang Electronics Tech Co

IBM

Intel Corporation

Qualcomm Technologies

STMicroelectronics

3M

Cisco Systems

## Semiconductor Packaging Market Insights

Lucintel forecast that flip chip will remain the largest type segment over the forecast period due to growing demand for advanced high-performance in electronics for retail and commercial application and increasing penetration of electronic devices globally.

Within this market, consumer electronics is projected to record the highest growth from 2023 to 2028 due to increasing smartphone market and increasing adoption of consumer IoT devices in applications, like smart homes.

APAC is expected to witness the highest growth during the forecast period due to rising disposable income of the people and their preferences for smart homes and smart business environments, well-established industrial and economic base for consumer electronics production, and the presence of major semiconductor manufacturing and processing countries such as China, Japan, and Taiwan.

## Features of the Semiconductor Packaging Market

**Market Size Estimates:** Semiconductor packaging market size estimation in terms of value (\$B)

**Trend And Forecast Analysis:** Market trends (2017-2022) and forecast (2023-2028) by various segments and regions.

**Segmentation Analysis:** Semiconductor packaging market size by various segments, such as by type, technology, end use industry, and region

**Regional Analysis:** Semiconductor packaging market breakdown by North America, Europe, Asia Pacific, and the Rest of the World.

**Growth Opportunities:** Analysis on growth opportunities in different by type, technology, end use industry, and regions for the semiconductor packaging market.

Strategic Analysis: This includes M&A, new product development, and competitive landscape for the semiconductor packaging market.

Analysis of competitive intensity of the industry based on Porter's Five Forces model.

## FAQ

Q1. What is the semiconductor packaging market size?

Answer: The global semiconductor packaging market is expected to reach an estimated \$29.2 billion by 2028.

Q2. What is the growth forecast for semiconductor packaging market?

Answer: The global semiconductor packaging market is expected to grow with a CAGR of 9.0% from 2023 to 2028.

Q3. What are the major drivers influencing the growth of the semiconductor packaging market?

Answer: The major drivers for this market are an increase in demand for advanced packaging in consumer electronics and industrial products along with growing trend of miniaturization globally.

Q4. What are the major segments for semiconductor packaging market?

Answer: The future of the semiconductor packaging market looks promising with opportunities in the consumer electronics, automotive, healthcare, IT & telecommunication, and aerospace & defense end use industries.

Q5. Who are the key semiconductor packaging companies?

Answer: Some of the key semiconductor packaging companies are as follows:

Amkor Technology

ASE Technology Holding Co.

Siliconware Precision Industries Co.

S?SS MICROTEC SE

Jiangsu Changjiang Electronics Tech Co

IBM

Intel Corporation

Qualcomm Technologies

STMicroelectronics

3M

Cisco Systems

Q6. Which semiconductor packaging segment will be the largest in future?

Answer: Lucintel forecast that flip chip will remain the largest type segment over the forecast period due to growing demand for advanced high-performance in electronics for retail and commercial application and increasing penetration of electronic devices globally.

Q7. In semiconductor packaging market, which region is expected to be the largest in next 5 years?

Answer: APAC is expected to witness the highest growth during the forecast period due to rising disposable income of the people and their preferences for smart homes and smart business environments, well-established industrial and economic base for consumer electronics production, and the presence of major semiconductor manufacturing and processing countries such as China, Japan, and Taiwan.

Q8. Do we receive customization in this report?

Answer: Yes, Lucintel provides 10% Customization Without any Additional Cost.

This report answers following 11 key questions

- Q.1. What are some of the most promising, high-growth opportunities for the global semiconductor packaging market by type (flip chip, embedded die, fan-in WLP, and fan-out WLP), technology (grid-array, small outline packaging, flat no-leads package, dual in-line packaging), end use industry (consumer electronics, automotive, healthcare, IT & telecommunication, and aerospace & defense), and region (North America, Europe, Asia Pacific, and the Rest of the World)?
- Q.2. Which segments will grow at a faster pace and why?
- Q.3. Which region will grow at a faster pace and why?
- Q.4. What are the key factors affecting market dynamics? What are the key challenges and business risks in this market?
- Q.5. What are the business risks and competitive threats in this market?
- Q.6. What are the emerging trends in this market and the reasons behind them?
- Q.7. What are some of the changing demands of customers in the market?
- Q.8. What are the new developments in the market? Which companies are leading these developments?
- Q.9. Who are the major players in this market? What strategic initiatives are key players pursuing for business growth?
- Q.10. What are some of the competing products in this market and how big of a threat do they pose for loss of market share by material or product substitution?
- Q.11. What M&A activity has occurred in the last 5 years and what has its impact been on the industry?

For any questions related to semiconductor packaging market or related to semiconductor packaging companies, semiconductor packaging market size, semiconductor packaging market share, semiconductor packaging analysis, write Lucintel analyst at email: [helpdesk@lucintel.com](mailto:helpdesk@lucintel.com) we will be glad to get back to you soon.

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7.6: IBM

7.7: Intel Corporation

7.8: Qualcomm Technologies

7.9: STMicroelectronics

7.10: 3M

7.11: Cisco Systems

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